



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-04-28
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	FLORIANA SAN BIAGIO	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LMV358IYPT	KD6P*V358AS6	A	BO2A	2017-04-28
	Amount	UoM	Unit type	ST ECOPACK Grade
	34.89	mg	Each	ECOPACK® 3
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3x4.4x1	8	gull wing	
Comment	Package: 6P TSSOP 8 BODY 4.4 PITCH 0.65			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	KD6P*V358AS6				4999999.0	1000029.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.447	mg	supplier	die	Silicon (Si)	7440-21-3		1.435	mg	991707	41135
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	3455	143
				supplier	Passivation	Silicon Nitride	12033-89-5		0.004	mg	2764	115
				supplier	Passivation	Silicon Oxide	7631-86-9		0.003	mg	2073	86
Leadframe	Copper & its alloys	11.618	mg	supplier	alloy	Copper (Cu)	7440-50-8		11.088	mg	954381	317844
				supplier	alloy	Nickel (Ni)	7440-02-0		0.346	mg	29781	9918
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.017	mg	1463	487
				supplier	alloy	Silicon (Si)	7440-21-3		0.075	mg	6456	2150
				supplier	metallization	Nickel (Ni)	7440-02-0		0.083	mg	7144	2379
				supplier	metallization	Palladium (Pd)	7440-05-3		0.003	mg	258	86
				supplier	metallization	Gold (Au)	7440-57-5		0.003	mg	258	86
Die attach	Other Organic Materials	0.554	mg	supplier	metallization	Silver (Ag)	7440-22-4		0.003	mg	258	86
				supplier	glue	Silver (Ag)	7440-22-4		0.485	mg	875451	13903
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.028	mg	50542	803
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.028	mg	50542	803
				supplier	glue	Acrylate polymer	87320-05-6		0.011	mg	19856	315
				supplier	glue	Epoxy cyclohexylethyltrimethoxysilane	3388-04-3		0.001	mg	1805	29
				supplier	glue	tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	1805	29
Bonding wires	Other inorganic materials	0.029	mg	supplier	wire	Copper (Cu)	7440-50-8		0.029	mg	1000000	831
Encapsulation	Other Organic Materials	21.238	mg	supplier	mold compound	Silica, vitreous	60676-86-0		18.625	mg	876966	533897
				supplier	mold compound	Epoxy resin	85954-11-6		0.850	mg	40023	24366
				supplier	mold compound	Epoxy	25068-38-6		0.850	mg	40023	24366
				supplier	mold compound	phenol resin	29690-82-2		0.637	mg	29993	18260
				supplier	mold compound	additive	Proprietary		0.212	mg	9982	6077
supplier	mold compound	carbon black	1333-86-4		0.064	mg	3013	1835				